

★FUJF

V04

2001-567352/64

★JP 2001036222-A

Printed circuit board for mounting semiconductor packages, includes recess in thread portion of land, so that adjoining solder balls do not form bridge when crushed during mounting of semiconductor device

FUJI PHOTO FILM CO LTD 1999.07.21 1999JP-205804

X24 (2001.02.09) //H01L 23/12, H05K 3/34

Novelty: A land (16) is provided on a printed circuit board (PCB) (15) corresponding to solder balls (14) provided in the electrode of a grid-array semiconductor device (11). A recess is provided in thread portion (16a) of the land, so that the adjoining solder balls do not form a bridge, when the solder ball is crushed by the semiconductor device.

Use: For mounting BGA, CSP, etc.

Advantage: Improves mounting operation efficiency by preventing generation of a bridge between solder balls.

Description of Drawing(s): The figure shows the top and side views of the condition of having mounted the grid-array semiconductor device on PCB.

Grid-array semiconductor device 11

Solder ball 14

PCB 15

Land 16

Thread portion 16a

(6pp Dwg.No.1/11)

N2001-422537

V04-Q05; X24-A01C

